



Device Material Content

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Package: 32 QFNS **with matte Sn Plating**
Total Device Weight 0.06 Grams

MSL: 1
Peak Reflow Temp: 260°C

April, 2012	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	3.43%	0.0021			Silicon chip	7440-21-3	Die size: 1.88 x 1.88 mm
Mold	63.40%	0.0380	55.79% 3.17% 3.17% 1.11% 0.16%	0.0335 0.0019 0.0019 0.0007 0.0001	Silica (fused) Epoxy Resin Phenol Resin Metal Hydroxide Carbon Black	60676-86-0 - - - 1333-86-4	Mold Compound Density ranges between 1.9 and 2.1 grams/cc 75 to 95% Fused silica filler (LSC uses 88% in our calculation) 2 to 10% Epoxy resin (LSC uses 5% in our calculation) 2 to 10% Phenol resin (LSC uses 5% in our calculation) 1 to 2% Metal Hydroxide (LSC uses 1.75% in our calculation) 0.1 to 0.5% Carbon Black (LSC uses 0.25% in our calculation)
D/A Epoxy	0.60%	0.0004	0.45% 0.15%	0.00027 0.00009	Silver (Ag) Organic esters and resins	7440-22-4 -	Die attach epoxy Density: 4 grams/cc 70 to 80% Silver (LSC uses 75% in our calculation) 20 to 30% Organic Resins, Hardners and Elastomers (LSC uses 25% in our calculation)
Wire	1.20%	0.0007			Gold (Au)	7440-57-5	Assume 1 wire per lead
Plating	0.56%	0.0003			Tin (Sn)	7440-31-5	Tin plating is 400 to 800 microinches (LSC uses 600 microinches in our calculation)
Leadframe	30.81%	0.0185	29.64% 0.92% 0.20% 0.05%	0.01778 0.00055 0.00012 0.00003	Copper (Cu) Nickel (Ni) Silicon (Si) Magnesium (Mg)	7440-50-8 7440-02-0 7440-21-3 7439-95-4	96.2% 3% 0.65% 0.15%

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
Constituent substances and proportions in epoxy materials are before curing.
The information provided above is representative of the package as of the date listed, and is subject to change at any time.
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